



Dear Valued Customer

Doc. No.: 2223007  
Issue date: September 1, 2023

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ROHM Co., Ltd.

### Notification of Product/Process Change

This is an announcement of change(s) to the process of the products currently supplied by ROHM Co., Ltd.

We request your acknowledgement of the receipt of this notification within the given period.

Please provide your your reply by March 31, 2024

Title of change	SiC 3G MOSFET TO-263-7L package: 6inch Wafer introduction and Wafer factory (to Miyazaki) change	
Affected product(s)	Manufacturer part number	Customer part number
	SCT3□□□□W7TL	
Detailed description of change	Before	After
	SiC wafer diameter: 4inch Wafer FAB: ROHM APOLLO Co., Ltd. Chikugo plant	SiC wafer diameter: 6inch Wafer FAB: LAPIS Semiconductor Co., Ltd. Miyazaki plant
Reason for change	- To increase production output by enhancing productivity and efficiency - End of production of 4-inch SiC wafers due to the transition to 6inch SiC wafers	
Anticipated impact on quality	There is no difference in reliability and electrical characteristics.	
Identification of change	Traceable by Lot code	
Planned first ship date :	April 1, 2024	Sample available schedule : September 1, 2023
Comments		

	Reply date	
Customer reply	<input type="checkbox"/> 1. Approved. <input type="checkbox"/> 2. Accepted with conditions.	
Condition for approval / reason for rejection		
Comments		
Customer company name		
Customer signature	Department	
Customer signature	Department	